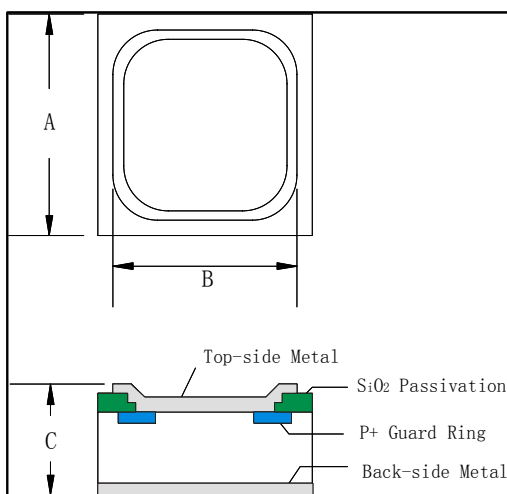


| | |
|---|---|
| SCHOTTKY DIE SPECIFICATION | TYPE: SB360 |
| General Description: 60 V 3 A (<input checked="" type="checkbox"/> Standard <input type="checkbox"/> Low) VF , | (<input checked="" type="checkbox"/> Single <input type="checkbox"/> Dual) Anode |

| ELECTRICAL CHARACTERISTICS | SYM | Spec. Limit | Die Sort | UNIT |
|---|--------|-------------|----------|------|
| DC Blocking Voltage: Ir=1mA(for wafer form) | VRRM | 60 | | Volt |
| Average Rectified Forward Current | IFAV | 3 | | Amp |
| Maximum Instantaneous Forward Voltage | | | | |
| @ 3 Ampere, Ta=25°C | VF MAX | 0.630 | | Volt |
| Reverse current | | | | |
| @ VR= 63 Volt, Ta=25°C | IR MAX | 0.150 | | mA |
| MAXIMUM RATINGS | | | | |
| Nonrepetitive Peak Surge Current | IFSM | 80 | | Amp |
| Operating Junction Temperature | Tj | 125 | | °C |
| Storage Temperature | TSTG | -50 to +150 | | °C |

Specifications apply to die only. Actual performance may degrade when assembled.
 We do not guarantee device performance after assembly.
 Data sheet information is subjected to change without notice.

DICE OUTLINE DRAWING



| DIM | ITEM | μ m | Mil |
|-----|--------------------|------|-------|
| A | Die Size | 1354 | 53.30 |
| B | Top Metal Pad Size | 1250 | 49.21 |
| C | Thickness (Min) | 280 | 11.00 |
| | Thickness (Max) | 300 | 11.80 |

PS:
 (1)Cutting street width is around 16 μ m (0.62mil).
 (2)Both of top-side and back-side metals are Ti/Ni/Ag.